



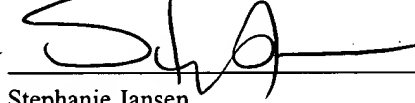
Correspondence and Mail
BOX AF

**RESPONSE UNDER 37 C.F.R. § 1.116
EXPEDITED PROCEDURE - EXAMINING GROUP 2800**

AF
2800

PATENT #24/B

I hereby certify that on the date specified below, this correspondence is being deposited with the United States Postal Service as first-class mail in an envelope addressed to Box AF, Commissioner of Patents, Washington, DC 20231.

October 24, 2002 
Date Stephanie Jansen

NOV 4 2002
MAIL ROOM

RECEIVED
N/E
J. McMillan
11/10/02

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant	: Tongbi Jiang	Attorney Docket No.	: 500182.01 (660073.774)
Serial No.	: 09/365,356	Group Art Unit	: 2813
Filed	: July 30, 1999	Examiner	: Nema O. Berezny
Title	: METHOD AND STRUCTURE FOR MANUFACTURING IMPROVED YIELD SEMICONDUCTOR PACKAGED DEVICES		

Box AF
Commissioner of Patents
Washington, DC 20231

RESPONSE UNDER 37 C.F.R. § 1.116

Sir:

Applicant acknowledges receipt of the Office Action dated September 11, 2002.

In the Claims:

Please amend claims 1, 11, 38 and 42 as follows:

1. (Four Times Amended) A semiconductor device package, comprising:
a semiconductor die having a first surface on which an integrated circuit and at least one electrically conductive bond pad are fabricated, the die having first and second pairs of opposed lateral edges;
at least one electrically conductive external terminal;